SDAS111B - APRIL 1982 - REVISED DECEMBER 1994

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

#### description

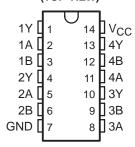
These devices contain four independent 2-input positive-NOR gates. They perform the Boolean functions  $Y = \overline{A} + \overline{B}$  or  $Y = \overline{A} \bullet \overline{B}$  in positive logic.

The SN54ALS02A and SN54AS02 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS02A and SN74AS02 are characterized for operation from 0°C to 70°C.

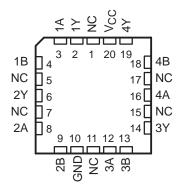
FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Χ	L
X	Н	L
L	L	Н

#### SN54ALS02A, SN54AS02...J PACKAGE SN74ALS02A, SN74AS02...D OR N PACKAGE (TOP VIEW)

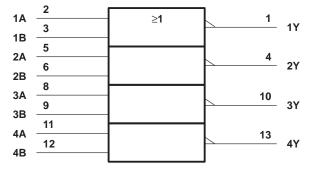


## SN54ALS02A, SN54AS02 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

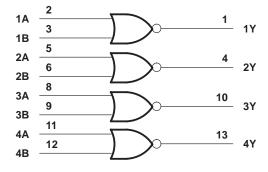
#### logic symbol†



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

#### logic diagram (positive logic)



### SN54ALS02A, SN54AS02, SN74ALS02A, SN74AS02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

SDAS111B - APRIL 1982 - REVISED DECEMBER 1994

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Operating free-air temperature range, T <sub>A</sub> : SN54ALS02A	-55°C to 125°C
SN74ALS02A	0°C to 70°C
Storage temperature range	-65°C to 150°C

#### recommended operating conditions

			SN	54ALS02	2A	SN	74ALS02		
		N	/IIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
.,	Land Land Country and Country				0.8‡			0.8	
VIL	Low-level input voltage				0.7§				V
lOH	High-level output current				-0.4			-0.4	mA
lOL	Low-level output current				4			8	mA
TA	Operating free-air temperature	-	-55		125	0		70	°C

<sup>‡</sup> Applies over temperature range -55°C to 70°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN5	4ALS0	2A	SN	74ALS02	2A		
PARAMETER	TEST CO	ONDITIONS	MIN	TYP¶	MAX	MIN	TYP¶	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.5			-1.5	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2	2		V
.,,	V 45V	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	.,
VOL	V <sub>CC</sub> = 4.5 V	$I_{OL} = 8 \text{ mA}$					0.35	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 7 V			0.1			0.1	mA
lін	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V			20			20	μΑ
I <sub>IL</sub>	$V_{CC} = 5.5 \text{ V},$	$V_{ } = 0.4 V$			-0.1			-0.1	mA
10 <sup>#</sup>	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
ІССН	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0		0.86	2.2		0.86	2.2	mA
ICCL	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 4.5 V		2.16	4		2.16	4	mA

<sup>¶</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>§</sup> Applies over temperature range 70°C to 125°C

<sup>#</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, Ios.

### SN54ALS02A, SN54AS02, SN74ALS02A, SN74AS02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

SDAS111B - APRIL 1982 - REVISED DECEMBER 1994

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> R <sub>L</sub>	$V_{CC}$ = 4.5 V to 5.5 V, $C_L$ = 50 pF, $R_L$ = 500 $\Omega$ , $T_A$ = MIN to MAX <sup>†</sup>					
	,	(,	SN54A	LS02A	SN74A				
			MIN	MAX	MIN	MAX			
t <sub>PLH</sub>	A or B	V	1	16	1	12			
t <sub>PHL</sub>	AUIB	· '	1	11	1	10	ns		

T For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	
Operating free-air temperature range, T <sub>A</sub> : SN54AS02	–55°C to 125°C
SN74AS02	0°C to 70°C
Storage temperature range	–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		S	N54AS0	2	S	N74AS0	N74AS02		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V	
$V_{IL}$	Low-level input voltage			0.8			0.8	V	
lOH	High-level output current			-2			-2	mA	
lOL	Low-level output current			20			20	mA	
TA	Operating free-air temperature	-55		125	0		70	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555		TEST CONDITIONS				S	N74AS0	2	LINUT
PARAMETER	IESI C	ONDITIONS	MIN	TYP§	MAX	MIN	TYP§	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	VCC -	2		VCC -2	2		V
VOL	V <sub>CC</sub> = 4.5 V,	$I_{OL} = 20 \text{ mA}$		0.35	0.5		0.35	0.5	V
lį	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
lіН	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 2.7 \text{ V}$			20			20	μΑ
I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.5			-0.5	mA
ΙΟ <sup>¶</sup>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	-30		-112	mA
Іссн	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0		3.7	5.9		3.7	5.9	mA
ICCL	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 4.5 V		12.5	20.1		12.5	20.1	mA

<sup>§</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los.



## SN54ALS02A, SN54AS02, SN74ALS02A, SN74AS02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

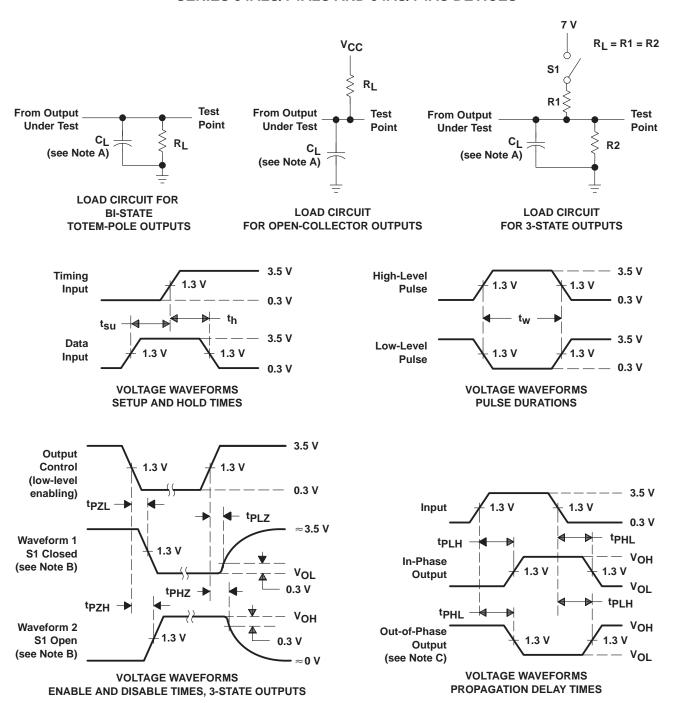
SDAS111B - APRIL 1982 - REVISED DECEMBER 1994

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VC C <sub>L</sub> R <sub>L</sub> T <sub>A</sub>	V, AS02	UNIT		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	V	1	6	1	4.5	20
t <sub>PHL</sub>	AUID	T	1	5	1	4.5	ns

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics:  $PRR \le 1$  MHz,  $t_f = t_f = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







24-Aug-2018

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86844012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86844012A SNJ54 ALS02AFK	Samples
5962-8684401DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684401DA SNJ54ALS02AW	Samples
JM38510/37301B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37301B2A	Samples
JM38510/37301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37301BCA	Samples
M38510/37301B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37301B2A	Samples
M38510/37301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37301BCA	Samples
SN54ALS02AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS02AJ	Samples
SN54AS02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS02J	Samples
SN74ALS02AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS02A	Samples
SN74ALS02ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS02A	Samples
SN74ALS02AN	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS02AN	Samples
SN74ALS02ANE4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS02AN	Samples
SN74ALS02ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS02A	Samples
SN74AS02D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS02	Samples
SN74AS02DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS02	Samples
SN74AS02N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS02N	Samples



#### PACKAGE OPTION ADDENDUM

24-Aug-2018

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	<b>Device Marking</b>	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74AS02NE4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS02N	Samples
SN74AS02NSR	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS02	Samples
SNJ54ALS02AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86844012A SNJ54 ALS02AFK	Samples
SNJ54ALS02AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54ALS02AJ	Samples
SNJ54ALS02AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684401DA SNJ54ALS02AW	Samples
SNJ54AS02FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54AS 02FK	Samples
SNJ54AS02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS02J	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



#### PACKAGE OPTION ADDENDUM

24-Aug-2018

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54ALS02A, SN54AS02, SN74ALS02A, SN74AS02:

Catalog: SN74ALS02A, SN74AS02

Military: SN54ALS02A, SN54AS02

NOTE: Qualified Version Definitions:

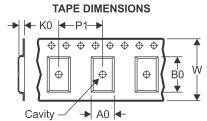
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

### PACKAGE MATERIALS INFORMATION

www.ti.com 8-Apr-2013

#### TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	
Γ	P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All difficults are norminal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS02ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS02DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS02NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

www.ti.com 8-Apr-2013



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS02ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74AS02DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74AS02NSR	SO	NS	14	2000	367.0	367.0	38.0

## FK (S-CQCC-N\*\*)

### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



#### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## W (R-GDFP-F14)

### CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



## D (R-PDSO-G14)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



## D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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